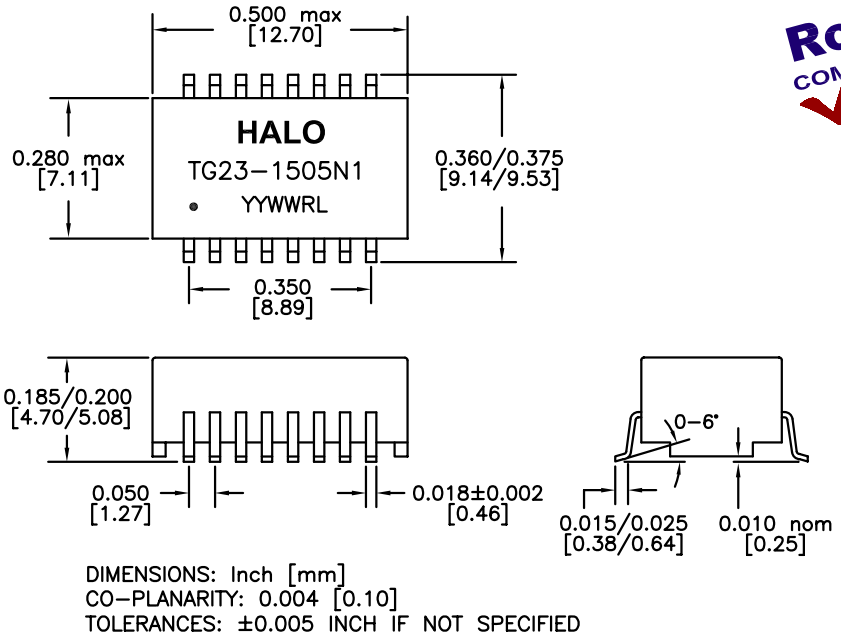
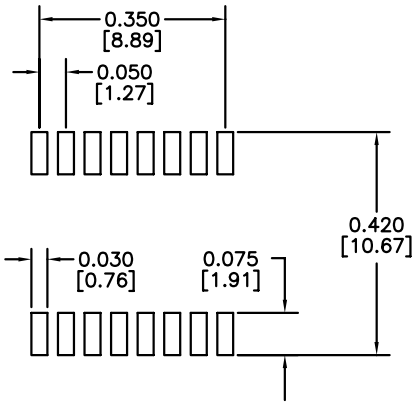
US PATENT NO. 5,656,985 6,297,720B1 6,297,721B1
6,320,489B1 6,344,785B1 6,662,431B1



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



RECOMMENDED SOLDER PAD DIMENSIONS

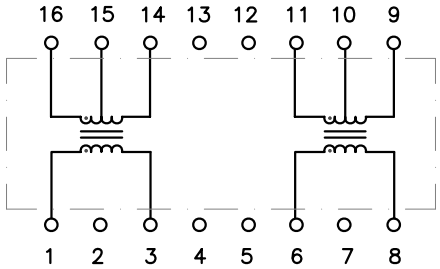
RoHS COMPLIANT

PART NO. : TG23-1505N1RL

16PIN DUAL SMT T1/E1 ISOLATION MODULE
RoHS COMPLIANT
COMPATIBLE TO LEAD-FREE SOLDERING PROCESS CONDITION PER IPC/JEDEC J-STD-020C
UL/EN60950 AND DEMKO REGOGNIZED
EXTENDED OPERATING TEMPERATURE -40/+85°C

ELECTRICAL SPECIFICATIONS @25° C

TURNS RATIO P1-3:P16-14,P6-8:P11-9	1:2.42CT±2%
OCL P1-3,P6-8	1.5mH typ
DCR P1-3,P6-8	0.8Ω max
Cw/w	35pF max
LL P1-3,P6-8	0.5μH max
CROSSTALK 0.5-5MHz	-60dB typ
ISOLATION	1,500Vrms



HALO/PBL
CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	SMT ISOLATION MODULE		
FOR	T1/E1 (1:2.42)		
PART NO.	TG23-1505N1RL		
SCALE	NONE	PAGE	1 OF 1

SIGNATURES		DATE	REV.	DESC.	DATE
DRAWN	LI ZHI ZHONG	4/13/05	A	FIRST ISSUE	4/13/05
CHECKED	LEI KEONG	10/26/10	B	UPDATE	10/24/05
APPROVED	PETER LU	10/26/10	C	PROD. RELEASE	10/26/10
FILE	1505N1RL.DWG				